



## Discription

The SP3031-01ETG protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one unidirectional line in applications where arrays are not practical.



DFN1006-2L  
(SOD-882)

## Features

- ★ Transient protection for high-speed data lines  
IEC 61000-4-2(ESD)  $\pm 20\text{kV}$  (Contact)  
 $\pm 20\text{kV}$  (Air)  
IEC 61000-4-4(EFT) 40A (5/50 ns)
- ★ Peak power dissipation: 60W (8/20 $\mu\text{s}$ )
- ★ Working voltages : 5V
- ★ Ultra-small package (1.0mmx0.6mmx0.5mm)
- ★ Protects one data, control line
- ★ Low capacitance: 0.4pF (Typical)
- ★ Low clamping voltage
- ★ Low leakage current



Circuit Diagram

## Ordering information

| Product ID   | Pack                 | Qty(PCS) |
|--------------|----------------------|----------|
| SP3031-01ETG | DFN1006-2L (SOD-882) | 10000    |

## Absolute Ratings(Tamb = 25°C)

| Symbol           | Parameter                                               | Value       | Units |
|------------------|---------------------------------------------------------|-------------|-------|
| P <sub>PP</sub>  | Peak Pulse Power (t <sub>p</sub> = 8/20 $\mu\text{s}$ ) | 60          | W     |
| T <sub>L</sub>   | Maximum lead temperature for soldering during 10s       | 260         | °C    |
| T <sub>stg</sub> | Storage Temperature Range                               | -55 to +150 | °C    |
| T <sub>op</sub>  | Operating Temperature Range                             | -55 to +150 | °C    |
| T <sub>j</sub>   | Maximum junction temperature                            | 150         | °C    |
|                  | IEC61000-4-2 (ESD) air discharge                        | $\pm 20$    | KV    |
|                  | contact discharge                                       | $\pm 20$    |       |
|                  | IEC61000-4-4 (EFT)                                      | 40          | A     |



**Electrical Characteristics** Ratings at 25°C

| Symbol    | Parameter                 | Test Condition                 | Min | Typ  | Max  | Units |
|-----------|---------------------------|--------------------------------|-----|------|------|-------|
| $V_{RWM}$ | Reverse Working Voltage   |                                |     |      | 5.0  | V     |
| $V_{BR}$  | Reverse Breakdown Voltage | $I_T = 1mA$                    | 6.0 |      |      | V     |
| $I_R$     | Reverse Leakage Current   | $V_{RWM} = 5V$                 |     |      | 100  | nA    |
| $V_C$     | Clamping Voltage          | $I_{PP} = 1A, t_p = 8/20\mu s$ |     |      | 10   | V     |
|           |                           | $I_{PP} = 4A, t_p = 8/20\mu s$ |     |      | 15   | V     |
| $C_J$     | Junction Capacitance      | $V_R = 0V, f = 1MHz$           |     | 0.60 | 0.80 | pF    |



## Typical Characteristics

Fig 1 Power Derating Curve

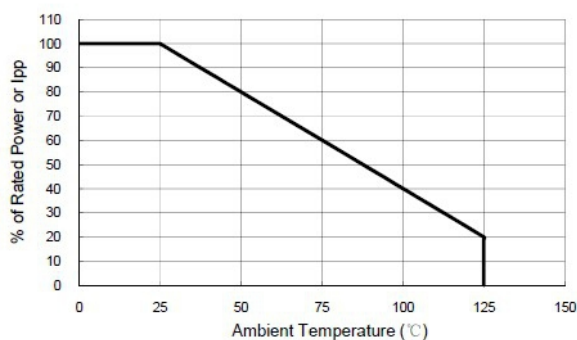


Fig 2 Clamping Voltage vs Peak Pulse Current

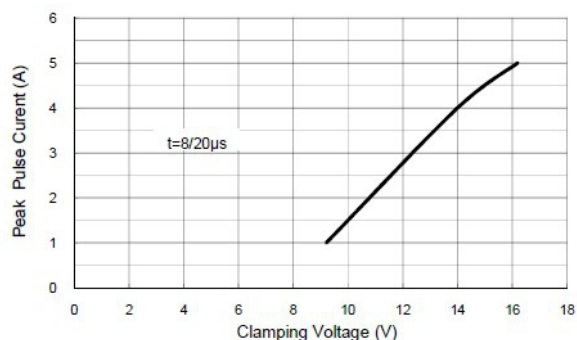


Fig 3 Voltage Sweeping

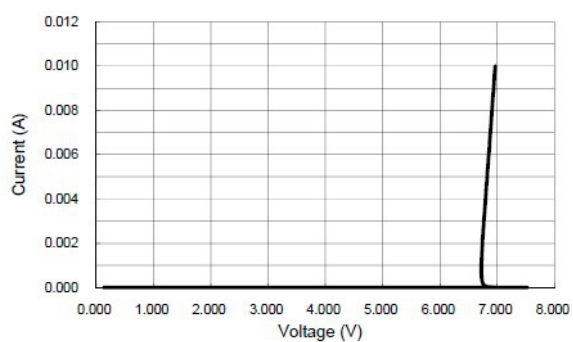


Fig 4 Voltage vs Capacitance

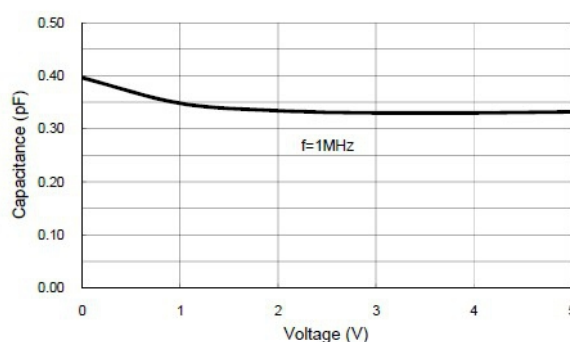


Fig 5 ESD Clamping  
(+8kV Contact per IEC 61000-4-2)

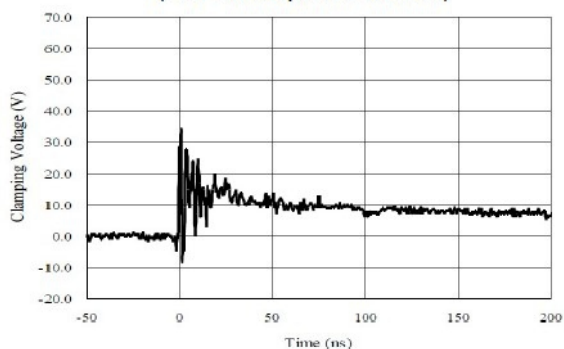
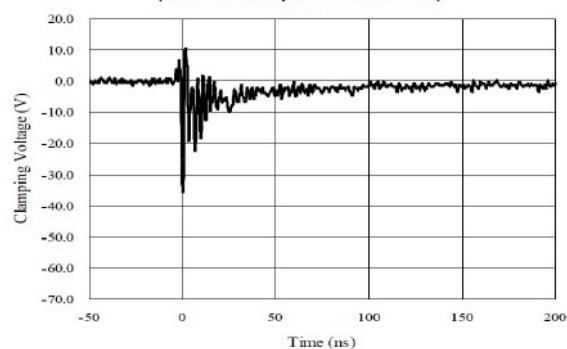
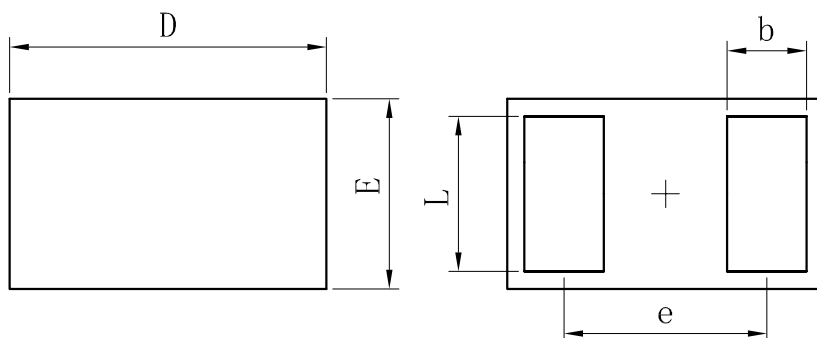


Fig 6 ESD Clamping  
(-8kV Contact per IEC 61000-4-2)



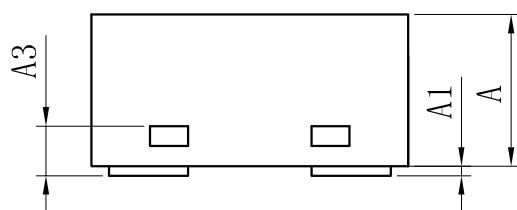


## Outline And Dimensions



TOP VIEW

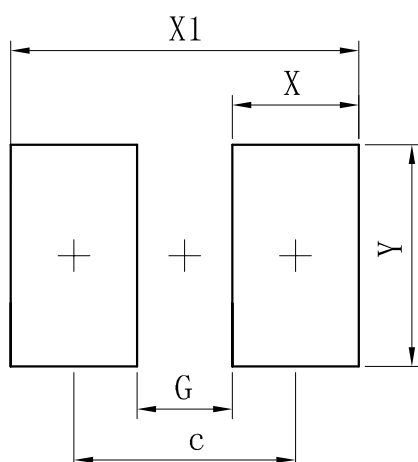
BOTTOM VIEW



SIDE VIEW

| DFN1006-2L(SOD-882)  |           |      |      |
|----------------------|-----------|------|------|
| Dim                  | Min       | Typ  | Max  |
| D                    | 0.95      | 1.00 | 1.05 |
| E                    | 0.55      | 0.60 | 0.65 |
| e                    | —         | 0.64 | —    |
| L                    | 0.44      | 0.49 | 0.54 |
| b                    | 0.20      | 0.25 | 0.30 |
| A                    | 0.43      | 0.48 | 0.53 |
| A1                   | 0         | —    | 0.05 |
| A3                   | 0.127REF. |      |      |
| All Dimensions in mm |           |      |      |

## Soldering Footprint



| Dimensions | (mm) |
|------------|------|
| c          | 0.70 |
| G          | 0.30 |
| X          | 0.40 |
| X1         | 1.10 |
| Y          | 0.70 |



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